

Title of Change:	Update of PB26418X to include additional statement
Effective date:	14 Sep 2025
Contact information:	Contact your local onsemi Sales Office
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi, ISMF Malaysia	None

Description and Purpose:

The original PB announced that onsemi will do optimization for substrate epi window.

Substrate	Before change	After change
R34A05T	Thickness (um): 10.4 - 11.6, Res (ohmcm): 2 - 2.4	Thickness (um): 10.7 - 11.6, Res (ohmcm): 1.9 - 2.25

This update notification is being issued to state that Datasheet specifications and electrical performance remain unchanged and No impact to Form, Fit, or Function of the affected part.

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

MBR1H100SFT3G	MBR2H100SFT3G	MBRM1H100T3G
MBRM2H100T3G	MBRA1H100T3G	